



40V N-Channel Enhancement Mode MOSFET

Voltage

40 V

Current

85 A

Features

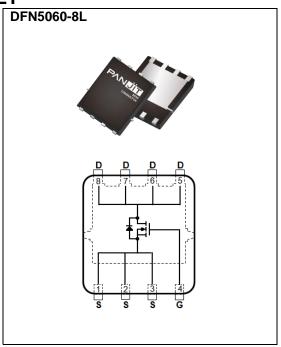
- Rds(on), Vgs@10V, Id@20A<5.3m Ω
- RDS(ON), VGS@4.5V, ID@20A<7.4m Ω
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

Mechanical Data

• Case: DFN5060-8L Package

• Terminals : Solderable per MIL-STD-750, Method 2026

• Approx. Weight: 0.08 grams



Maximum Ratings and Thermal Characteristics (T_A=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS	
Drain-Source Voltage		V _{DS}	40	V	
Gate-Source Voltage		V_{GS}	±20	V	
Continuous Drain Current(Note 3)	T _C =25°C	l _D	85	А	
	T _C =100°C		60		
Pulsed Drain Current(Note 1)	T _C =25°C	I _{DM}	340		
Power Dissipation	T _C =25°C	Po	68	W	
	T _C =100°C		34		
Continuous Drain Current(Note 4)	T _A =25°C	I _D	18.7		
	T _A =70°C		15.6	Α	
Power Dissipation	T _A =25°C	PD	3.3	W	
	T _A =70°C		2.3		
Single Pulse Avalanche Energy ^(Note 5)		Eas	90	mJ	
Operating Junction and Storage Temperature Range		T _J ,T _{STG}	-55~175	°C	
Thermal Resistance ^(Note 4)	Junction to Case	$R_{ heta JC}$	2.2	°C/W	
	Junction to Ambient	$R_{\theta JA}$	45		





Electrical Characteristics (T_A=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS	
Static	_						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA 40		-	-		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =50uA	1.1	1.7	2.3	V	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	4.2	5.3	mΩ	
		V _{GS} =4.5V, I _D =20A	-	5.7	7.4		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V, V _{GS} =0V	-	-	1	uA	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
Dynamic ^(Note 6)							
Total Gate Charge	Q_g	V _{DS} =32V, I _D =20A,	-	20	-		
Gate-Source Charge	Q_{gs}		-	3.1	-	nC	
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	6.4	-		
Input Capacitance	Ciss)/ OF)/)/ O)/	-	1320	-	pF	
Output Capacitance	Coss	V _{DS} =25V, V _{GS} =0V,	-	250	-		
Reverse Transfer Capacitance	Crss	f=1MHz	-	30	-		
Gate resistance	Rg	f=1MHz	-	0.8	-	Ω	
Turn-On Delay Time	td _(on)	.,	-	11	-		
Turn-On Rise Time	tr	V _{DS} =32V, I _D =20A,	-	3	-		
Turn-Off Delay Time	td _(off)	$V_{GS}=10V, R_{G}=3\Omega$	-	28	-	ns	
Turn-Off Fall Time	tf	(Note 2)	-	5	-		
Drain-Source Diode						•	
Diode Forward Current	Is	T _C =25°C	-	-	85	A	
Pulsed Diode Forward Current	I _{SM}	1c=25 C	-	-	340		
Diode Forward Voltage	V _{SD}	Is=20A, V _{GS} =0V	-	0.85	1.3	V	
Reverse Recovery Time	Trr	V _{GS} =0V, I _S =20A	-	23	-	ns	
Reverse Recovery Charge	Qrr	dls/dt=100A/us	-	15	-	nC	

NOTES:

- Pulse width≤100us, Duty cycle≤2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an R_{eJC}=2.2°C/W.
- 4. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch² with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I_{AS}=19A, V_{DD}=25V, V_{GS}=10V, Starting T_J=25°C.
- 6. Guaranteed by design, not subject to production testing.





TYPICAL CHARACTERISTIC CURVES

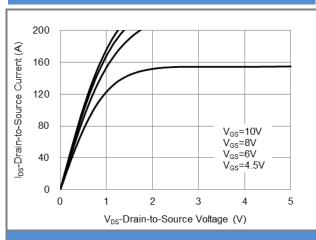


Fig.1 On-Region Characteristics

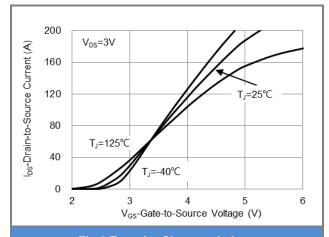


Fig.2 Transfer Characteristics

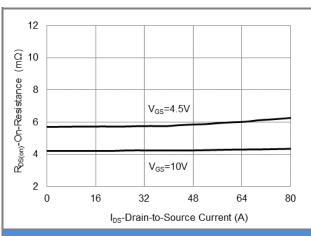


Fig.3 On-Resistance vs. Drain Current

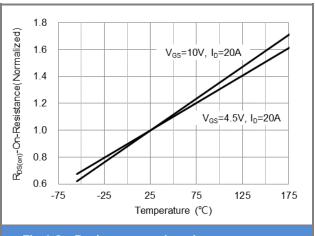
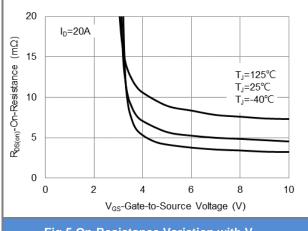
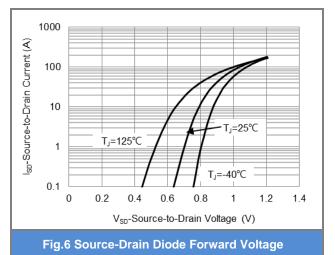


Fig.4 On-Resistance vs. Junction temperature











TYPICAL CHARACTERISTIC CURVES

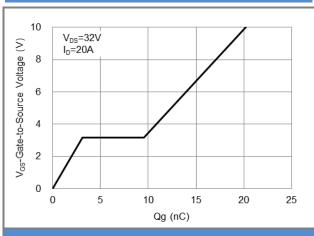


Fig.7 Gate-Charge Characteristics

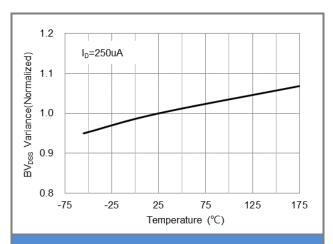


Fig.8 Breakdown Voltage Variation vs. Temperature

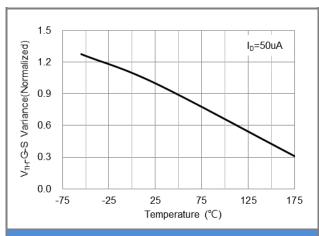


Fig.9 Threshold Voltage Variation with Temperature

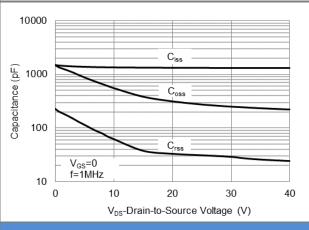


Fig.10 Capacitance vs. Drain-Source Voltage

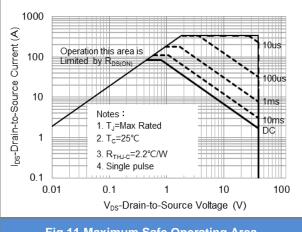


Fig.11 Maximum Safe Operating Area

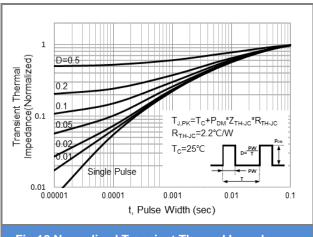


Fig.12 Normalized Transient Thermal Impedance

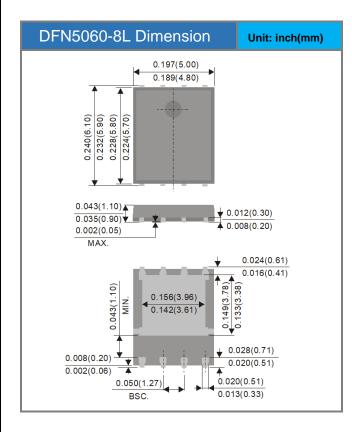


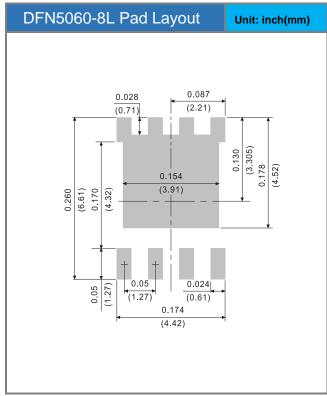


Product and Packing Information

Part No.	Package Type	Packing Type	Marking	
PJQ5546-AU	DFN5060-8L	3K pcs / 13" reel	Q5546	

Packaging Information & Mounting Pad Layout









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